

Description

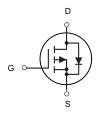
The DMP6185SK3 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



General Features

 $V_{DS} = -60V I_{D} = -10 A$

 $R_{DS(ON)}$ < 140m Ω @ V_{GS} =10V



Application

Brushless motor

Load switch

Uninterruptible power supply

P-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
DMP6185SK3	TO-252-2L	HXY MOSFET	2500

Absolute Maximum Ratings (T_c=25^oCunless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	-60	V
Vgs	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ -10V ¹	-10	Α
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ -10V ¹	-8.3	А
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ -10V ¹	-3.3	Α
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ -10V ¹	-2.7	Α
Ідм	Pulsed Drain Current ²	-26	Α
EAS	Single Pulse Avalanche Energy ³	29.8	mJ
las	Avalanche Current	-24.4	Α
P _D @T _C =25°C	Total Power Dissipation ⁴	31.3	W
P _D @T _A =25°C	Total Power Dissipation ⁴	2	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
R _θ JA	Thermal Resistance Junction-Ambient ¹	62	°C/W
R _θ JC	Thermal Resistance Junction-Case ¹	4.0	°C/W



P-Channel Electrical Characteristics (TJ =25 $^{\circ}$ C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-60			V	
∆BVDSS/∆TJ	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA	nA0.03		-	V/°C	
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-3A		125	140	mΩ	
1120(011)	V _{GS} =-4.5V , I _D =-2A			185	200	11132	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$, I_D =-250uA	-1.2	1.6	-2.5	V	
IDSS	Drain-Source Leakage Current	V _{DS} =-48V , V _{GS} =0V , T _J =25°C			1	uA	
1033		V _{DS} =-48V , V _{GS} =0V , T _J =55°C			5		
IGSS	Gate-Source Leakage Current	V_{GS} =±20 V , V_{DS} =0 V			±100	nA	
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-3A		8.5		S	
Qg	Total Gate Charge (-4.5V)	V _{DS} =-48V , V _{GS} =-4.5V , I _D =-3A		12.1		nC	
Qgs	Gate-Source Charge			2.2			
Qgd	Gate-Drain Charge			6.3			
Td(on)	Turn-On Delay Time	V _{DD} =-15V , V _{GS} =-10V , R _G =3.3□, I _D =-1A		9.2			
Tr	Rise Time			20.1		no	
Td(off)	Turn-Off Delay Time			46.7		ns	
Tf	Fall Time			9.4			
Ciss	Input Capacitance			1137			
Coss	Output Capacitance	V_{DS} =-15V , V_{GS} =0V , f=1MHz		76		pF	
Crss	Reverse Transfer Capacitance			50			
IS	Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current			-13	Α	
VSD	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C			-1.2	٧	

Note:

- 1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3. The EAS data shows Max. rating . The test condition is V DD =-25V,V GS =-10V,L=0.1mH,IAS =-24A
- 5. The data is theoretically the same as I D and I DM, in real applications, should be limited by total power dissipation.



P-Channel Typical Characteristics

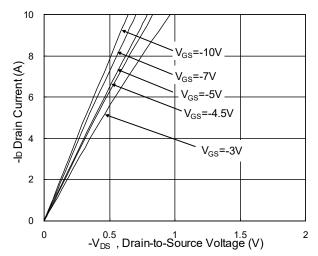


Fig.1 Typical Output Characteristics

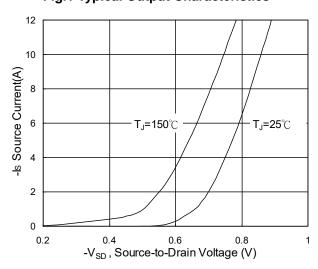


Fig.3 Forward Characteristics of Reverse

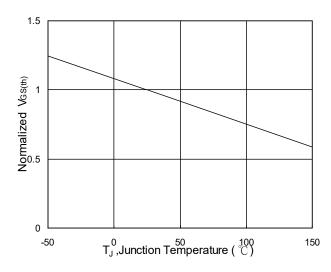


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

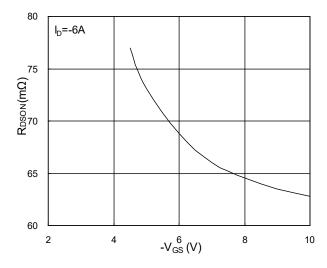


Fig.2 On-Resistance v.s Gate-Source

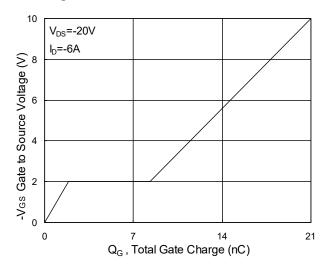


Fig.4 Gate-Charge Characteristics

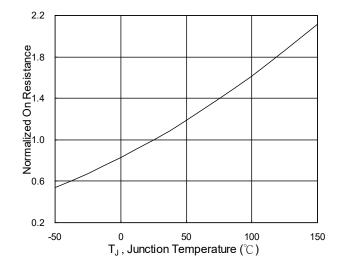
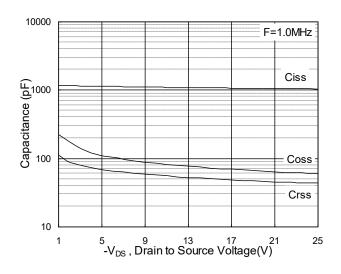


Fig.6 Normalized R_{DSON} v.s T_J





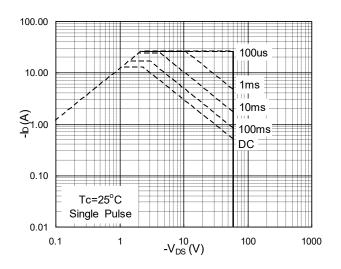


Fig.7 Capacitance

Fig.8 Safe Operating Area

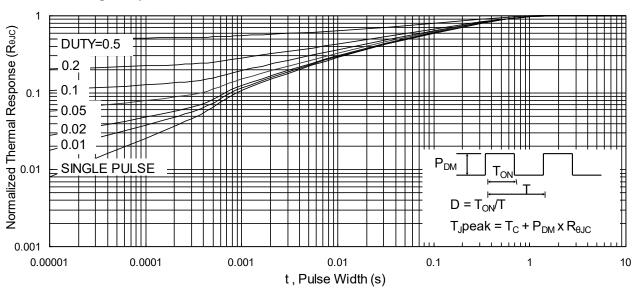


Fig.9 Normalized Maximum Transient Thermal Impedance

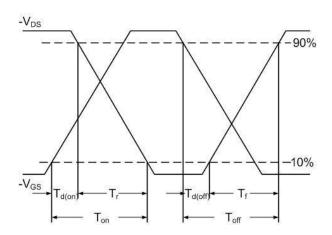


Fig.10 Switching Time Waveform

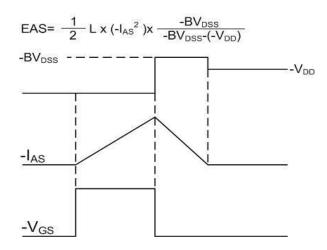
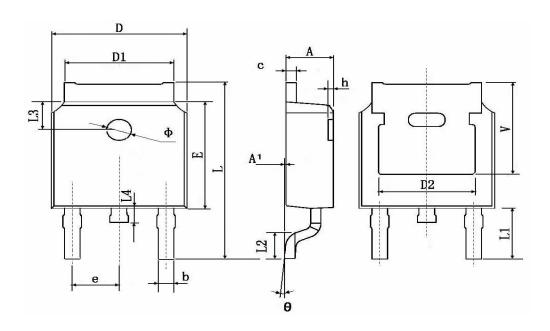


Fig.11 Unclamped Inductive Switching Waveform



TO-252-2L Package Information



	Dimensions In Millimeters		Dimensions In Inches			
Symbol	Min.	Max.	Min.	Max.		
A	2.200	2.400	0.087	0.094		
A1	0.000	0.127	0.000	0.005		
b	0.660	0.860	0.026	0.034		
С	0.460	0.580	0.018	0.023		
D	6.500	6.700	0.256	0.264		
D1	5.100	5.460	0.201	0.215		
D2	4.830	4.830 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244		
е	2.186	2.386	0.086	0.094		
L	9.800	10.400	0.386	0.409		
L1	2.900) TYP.	0.114 TYP.			
L2	1.400	1.700	0.055	0.067		
L3	1.600 TYP.		0.063 TYP.			
L4	0.600	1.000	0.024	0.039		
Ф	1.100	1.300	0.043	0.051		
θ	0°	8°	0°	8°		
h	0.000	0.300	0.000	0.012		
V	5.350) TYP.	0.211 TYP.			



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